



# **TG-A730AB / S730AB Silicone Potting Compound**

REACH Compliant

RoHS Compliant

#### **Features**

- · Good thermal conductivity
- · Cures at room temperature or with heat
- · A:B = 1:1
- · Pistol friendly & easy assembly
- · Low viscosity

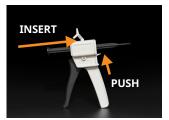
## **Applications**

Electronic Components - 5G, Aerospace, AI, AIoT, AR/VR/MR/XR, Automotive, Consumer Devices, Datacom, Electric Vehicle, Electronic Products, Energy Storage, Industrial, Lighting Equipment, Medical, Military, Netcom, Panel, Power Electronics, Robot, Servers, Smart Home, Telecom, etc.

#### **Storage**

Silicone Potting Compound has a shelf-life of 12 months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened container at or below 25°C.

### **Operation Manual**







1) Push the latch and insert the stick.

2 Put the tube in.

3 Close the cover.

#### **Properties**

Thermal Conductivity: 2.1 W/m·K

Hardness: 60 (Shore A) 0.8 1.2 1.4 1.6 1.7 1.8 2.2 3.2 3.6 4.0 4.5 5.0

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|------------------------------|---------|--------------------|---------------|-----------------------|
| Properties                   | Unit    | TG-A730AB / S730AB | Tolerance     | Test Method           |
| Thermal Conductivity         | W/m·K   | 2.1                | ±10%          | ASTM D5470 Modified   |
| Color                        | -       | Gray               | -             | -                     |
| Dielectric Breakdown Voltage | kV/mm   | ≥11                | -             | ASTM D149             |
| Volume Resistivity           | Ohm∙m   | 1*10 <sup>12</sup> | -             | ASTM D257             |
| Density                      | g/cm³   | 2.3                | ±5%           | ASTM D792             |
| Operating Temperature        | ° C     | -50~+200           | -             | -                     |
| Viscosity                    | Pa∙s    | 6~12               | -             | Brookfield Viscometer |
| Curing Time @25° C           | min     | 180                | -             | -                     |
| Curing Time @60° C           | min     | 15                 | -             | -                     |
| Curing Time @100° C          | min     | 5                  | -             | -                     |
| Standard Package             | -       | Tube/Pot           | -             | -                     |
| Hardness                     | Shore A | 60                 | ±10           | ASTM D2240            |
| Mixing Ratio                 | gram    | 1:1                | -             | -                     |

Component A is a mixed material of silicone and thermal conductive powder. It is normal to cause precipitation and stratification due to different density. Well mixed component A before use by a flat spatula or other stainless tools to achieve the ideal thermal conductivity.

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